

**SLVS638B–MAY 2006–REVISED JANUARY 2007**

## **FEATURES**

- • **Fixed 3.3-V, 5-V, 12-V, and 15-V Options With** <sup>±</sup>**5% Regulation (Max) Over Line, Load, and Temperature Conditions**
- • **Adjustable Option With <sup>a</sup> Range of 1.23 V to 37 V (57 V for HV Version) and** <sup>±</sup>**4% Regulation (Max) Over Line, Load, and Temperature Conditions**
- •**Specified 1-A Output Current**
- • **Wide Input Voltage Range**…**4.75 V to 40 V (60 V for HV Version)**
- **Require Only Four External Components (Fixed Versions) and Use Readily Available Standard Inductors**
- • **52-kHz (Typ) Fixed-Frequency Internal Oscillator**
- • **TTL Shutdown Capability With 50-**µ**A (Typ) Standby Current**
- •**High Efficiency**…**as High as 88% (Typ)**
- • **Thermal Shutdown and Current-Limit Protection With Cycle-by-Cycle Current Limiting**

## **APPLICATIONS**

- • **Simple High-Efficiency Step-Down (Buck) Regulators**
- •**Pre-Regulators for Linear Regulators**
- •**On-Card Switching Regulators**
- •**Positive-to-Negative Converters (Buck-Boost)**





## **DESCRIPTION/ORDERING INFORMATION**

The TL2575 and TL2575HV greatly simplify the design of switching power supplies by conveniently providing all the active functions needed for <sup>a</sup> step-down (buck) switching regulator in an integrated circuit. Accepting <sup>a</sup> wide input voltage range of up to 60 V (HV version) and available in fixed output voltages of 3.3 V, 5 V, 12 V, 15 V, or an adjustable-output version, the TL2575 and TL2575HV have an integrated switch capable of delivering 1 A of load current, with excellent line and load regulation. The device also offers internal frequency compensation, <sup>a</sup> fixed-frequency oscillator, cycle-by-cycle current limiting, and thermal shutdown. In addition, <sup>a</sup> manual shutdown is available via an external ON/OFF pin.

The TL2575 and TL2575HV represent superior alternatives to popular three-terminal linear regulators. Due to their high efficiency, the devices significantly reduce the size of the heatsink and, in many cases, no heatsink is required. Optimized for use with standard series of inductors available from several different manufacturers, the TL2575 and TL2575HV greatly simplify the design of switch-mode power supplies by requiring <sup>a</sup> minimal addition of only four to six external components for operation.

The TL2575 and TL2575HV are characterized for operation over the virtual junction temperature range of –40°C to 125°C.



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#### **ORDERING INFORMATION(1) TL2575 (VIN(MAX) <sup>=</sup> <sup>40</sup> V)**



(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

(2) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



#### **ORDERING INFORMATION(1) TL2575HV (VIN(MAX) <sup>=</sup> <sup>60</sup> V)**

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

(2) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

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A. Pin numbers are for the KTT (TO-263) package.



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**Figure 1. Typical Application Circuit (Fixed Version)**

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### **Absolute Maximum Ratings (1)**

over operating free-air temperature range (unless otherwise noted)



(1) Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under recommended operating conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

## **Package Thermal Data (1)**



(1) Maximum power dissipation is a function of  $T_J(max)$ ,  $\theta_{JA}$ , and  $T_A$ . The maximum allowable power dissipation at any allowable ambient temperature is  ${\sf P_D}$  = (T $_{\sf J}$ (max) – T<sub>A</sub>)/ $\theta_{\sf J A}$ . Operating at the absolute maximum T $_{\sf J}$  of 150°C can affect reliability.

(2) For packages with exposed thermal pads, such as QFN, PowerPAD™, or PowerFLEX™, θ<sub>JP</sub> is defined as the thermal resistance between the die junction and the bottom of the exposed pad.

### **Recommended Operating Conditions**



## **TL2575 Electrical Characteristics**

 $I_{LOAD}$  = 200 mA, V<sub>IN</sub> = 12 V for 3.3-V, 5-V, and adjustable versions, V<sub>IN</sub> = 25 V for 12-V version, V<sub>IN</sub> = 30 V for 15-V version (unless otherwise noted) (see [Figure](#page-8-0) 2)



(1) In the event of an output short or an overload condition, self-protection features lower the oscillator frequency to <sup>∼</sup>18 kHz and the minimum duty cycle from 5% to <sup>∼</sup>2%. The resulting output voltage drops to <sup>∼</sup>40% of its nominal value, causing the average power dissipated by the IC to lower.

(2) Output is not connected to diode, inductor, or capacitor. Output is sourcing current.

(3) FEEDBACK is disconnected from output and connected to 0 V.

(4) To force the output transistor off, FEEDBACK is disconnected from output and connected to 12 V for the adjustable, 3.3-V, and 5-V versions and to 25 V for the 12-V and 15-V versions.



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### **TL2575 Electrical Characteristics (continued)**

 $I_{LOAD}$  = 200 mA, V<sub>IN</sub> = 12 V for 3.3-V, 5-V, and adjustable versions, V<sub>IN</sub> = 25 V for 12-V version, V<sub>IN</sub> = 30 V for 15-V version (unless otherwise noted) (see [Figure](#page-8-0) 2)



## **TL2575HV Electrical Characteristics**

 $I_{LOAD}$  = 200 mA, V<sub>IN</sub> = 12 V for 3.3-V, 5-V, and adjustable versions, V<sub>IN</sub> = 25 V for 12-V version, V<sub>IN</sub> = 30 V for 15-V version (unless otherwise noted) (see [Figure](#page-8-0) 2)



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### **TL2575HV Electrical Characteristics (continued)**

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#### **TEST CIRCUITS**

<span id="page-8-0"></span>

**CIN = 100** µ**F, Aluminum Electrolytic COUT = 330** µ**F, Aluminum Electrolytic D1 = Schottky**

**L1 = 330** μH (for 5-V V<sub>IN</sub> with 3.3-V V<sub>OUT</sub>, use 100 μH)



**VOUT = VREF(1 + R2/R1) = 5 V**

**VREF = 1.23 V**  $R1 = 2 k\Omega$ **R2 = 6.12 k**

A. Pin numbers are for the KTT (TO-263) package.

#### **Figure 2. Test Circuits and Layout Guidelines**

## **TYPICAL CHARACTERISTICS**



**Figure 3. Normalized Output Voltage Figure 4. Line Regulation**



**Figure 5. Dropout Voltage Figure 6. Current Limit**





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## **TYPICAL CHARACTERISTICS (continued)**









**Figure 7. Quiescent Current Figure 8. Standby Quiescent Current**



**Figure 9. Oscillator Frequency Figure 10. Switch Saturation Voltage**



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## **TYPICAL CHARACTERISTICS (continued)**



- A. Output pin voltage, 10 V/Div
- B. Output pin current, 1 A/Div
- C. Inductor current, 0.5 A/Div
- D. Ouput ripple voltage, 20 mV/Div



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**Figure 14. Load Transient Response**



## **APPLICATION INFORMATION**

### **Input Capacitor (C<sub>IN</sub>)**

For stability concerns, an input bypass capacitor (electrolytic, C<sub>IN</sub> ≥ 47 µF) needs to be located as close as possible to the regulator. For operating temperatures below –25°C, C<sub>IN</sub> may need to be larger in value. In addition, since most electrolytic capacitors have decreasing capacitances and increasing ESR as temperature drops, adding <sup>a</sup> ceramic or solid tantalum capacitor in parallel increases the stability in cold temperatures.

To extend the capacitor operating lifetime, the capacitor RMS ripple current rating should be:

 $\mathsf{I}_{\mathsf{C},\mathsf{RMS}}$  > 1.2( $\mathsf{t}_{\mathsf{on}}$ /T) $\mathsf{I}_{\mathsf{LOAD}}$ 

where

 $t_{on}/T = V_{OUT}/V_{IN}$  {buck regulator} and

 $t_{on}/T = |V_{OUT}|/(|V_{OUT}| + V_{IN})$  {buck-boost regulator}

## **Output Capacitor (C<sub>OUT</sub>)</del>**

For both loop stability and filtering of ripple voltage, an output capacitor also is required, again in close proximity to the regulator. For best performance, low-ESR aluminum electrolytics are recommended, although standard aluminum electrolytics may be adequate for some applications. Based on the following equation:

Output ripple voltage = (ESR of  $C_{OUT}$ ) × (inductor ripple current)

Output ripple of 50 mV to 150 mV typically can be achieved with capacitor values of 220 µF to 680 µF. Larger  $C<sub>OUT</sub>$  can reduce the ripple 20 mV to 50 mV peak to peak. To improve further on output ripple, paralleling of standard electrolytic capacitors may be used. Alternatively, higher-grade capacitors such as high frequency, low inductance, or low ESR can be used.

The following should be taken into account when selecting  $C_{\text{OUT}}$ .

- • At cold temperatures, the ESR of the electrolytic capacitors can rise dramatically (typically 3<sup>×</sup> nominal value at –25°C). Because solid tantalum capacitors have significantly better ESR specifications at cold temperatures, they should be used at operating temperature lower than –25°C. As an alternative, tantalums also can be paralleled to aluminum electrolytics and should contribute 10% to 20% to the total capacitance.
- •Low ESR for C<sub>OUT</sub> is desirable for low output ripple. However, the ESR should be greater than 0.05 Ω to avoid the possibility of regulator instability. Hence, a sole tantalum capacitor used for  $C<sub>OUT</sub>$  is most susceptible to this occurrence.
- • The capacitor's ripple current rating of 52 kHz should be at least 50% higher than the peak-to-peak inductor ripple current.

### **Catch Diode**

As with other external components, the catch diode should be placed close to the output to minimize unwanted noise. Schottky diodes have fast switching speeds and low forward voltage drops and, thus, offer the best performance, especially for switching regulators with low output voltages ( $V_{\text{OUT}}$  < 5 V). If a high-efficiency, fast-recovery, or ultra-fast-recovery diode is used in place of <sup>a</sup> Schottky, it should have <sup>a</sup> soft recovery (versus abrupt turn-off characteristics) to avoid the chance of causing instability and EMI. Standard 50-/60-Hz diodes, such as the 1N4001 or 1N5400 series, are not suitable.

## **APPLICATION INFORMATION (continued)**

#### **Inductor**

Proper inductor selection is key to the performance-switching power-supply designs. One important factor to consider is whether the regulator is used in continuous mode (inductor current flows continuously and never drops to zero) or in discontinuous mode (inductor current goes to zero during the normal switching cycle). Each mode has distinctively different operating characteristics and, therefore, can affect the regulator performance and requirements. In many applications, the continuous mode is the preferred mode of operation, since it offers greater output power with lower peak currents, and also can result in lower output ripple voltage. The advantages of continuous mode of operation come at the expense of <sup>a</sup> larger inductor required to keep inductor current continuous, especially at low output currents and/or high input voltages.

The TL2575 and TL2575HV can operate in either continuous or discontinuous mode. With heavy load currents, the inductor current flows continuously and the regulator operates in continuous mode. Under light load, the inductor fully discharges and the regulator is forced into the discontinuous mode of operation. For light loads (approximately 200 mA or less), this discontinuous mode of operation is perfectly acceptable and may be desirable solely to keep the inductor value and size small. Any buck regulator eventually operates in discontinuous mode when the load current is light enough.

The type of inductor chosen can have advantages and disadvantages. If high performance/quality is <sup>a</sup> concern, then more-expensive toroid core inductors are the best choice, as the magnetic flux is contained completely within the core, resulting in less EMI and noise in nearby sensitive circuits. Inexpensive bobbin core inductors, however, generate more EMI as the open core does not confine the flux within the core. Multiple switching regulators located in proximity to each other are particularly susceptible to mutual coupling of magnetic fluxes from each other's open cores. In these situations, closed magnetic structures (such as <sup>a</sup> toroid, pot core, or E-core) are more appropriate.

Regardless of the type and value of inductor used, the inductor never should carry more than its rated current. Doing so may cause the inductor to saturate, in which case the inductance quickly drops, and the inductor looks like <sup>a</sup> low-value resistor (from the dc resistance of the windings). As <sup>a</sup> result, switching current rises dramatically (until limited by the current-by-current limiting feature of the TL2575 and TL2575HV) and can result in overheating of the inductor and the IC itself. Note that different types of inductors have different saturation characteristics.

### **Output Voltage Ripple and Transients**

As with any switching power supply, the output of the TL2575 and TL2575HV have <sup>a</sup> sawtooth ripple voltage at the switching frequency. Typically about 1% of the output voltage, this ripple is due mainly to the inductor sawtooth ripple current and the ESR of the output capacitor (see note on  $C_{OUT}$ ). Furthermore, the output also may contain small voltage spikes at the peaks of the sawtooth waveform. This is due to the fast switching of the output switch and the parasitic inductance of  $C_{OUT}$ . These voltage spikes can be minimized through the use of low-inductance capacitors.

There are several ways to reduce the output ripple voltage: a larger inductor, a larger  $C_{\text{OUT}}$ , or both. Another method is to use a small LC filter (20  $\mu$ H and 100  $\mu$ F) at the output. This filter can reduce the output ripple voltage by <sup>a</sup> factor of 10 (see [Figure](#page-8-0) 2).

### **Feedback Connection**

For fixed-voltage options, FEEDBACK must be wired to  $V_{OUT}$ . For the adjustable version, FEEDBACK must be connected between the two programming resistors. Again, both of these resistors should be in close proximity to the regulator, and each should be less than 100 kΩ to minimize noise pickup.

## **ON/OFF Input**

ON/OFF should be grounded or be <sup>a</sup> low-level TTL voltage (typically <1.6 V) for normal operation. To shut down the TL2575 or TL2575HV and put it in standby mode, <sup>a</sup> high-level TTL or CMOS voltage should be supplied to this pin.  $\overline{ON}/\overline{OFF}$  should not be left open and safely can be pulled up to  $V_{\text{IN}}$  with or without a pullup resistor.

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## **APPLICATION INFORMATION (continued)**

#### **Grounding**

The power and ground connections of the TL2575 and TL2575HV must be low impedance to help maintain output stability. For the 5-pin packages, both pin 3 and tab are ground, and either connection can be used as they are both part of the same lead frame. With the 16-pin package, all the ground pins (including signal and power grounds) should be soldered directly to wide PCB copper traces to ensure low-inductance connections and good thermal dissipation.

#### **Layout Guidelines**

With any switching regulator, circuit layout plays an important role in circuit performance. Wiring and parasitic inductances, as well as stray capacitances, are subjected to rapidly switching currents, which can result in unwanted voltage transients. To minimize inductance and ground loops, the length of the leads indicated by heavy lines should be minimized. Optimal results can be achieved by single-point grounding (see [Figure](#page-8-0) 2) or by ground-plane construction. For the same reasons, the two programming resistors used in the adjustable version should be located as close as possible to the regulator to keep the sensitive feedback wiring short.

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## **BUCK REGULATOR DESIGN PROCEDURE**



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## <span id="page-18-0"></span>**Inductor Value Selection Guide for Continuous-Mode Operation**



**Figure 19. TL2575-ADJ**

<span id="page-19-0"></span>

#### **Table 1. Diode Selection Guide**

#### **Table 2. Inductor Selection by Manufacturer's Part Number**



(1) Schott Corporation, (612) 475-1173, 1000 Parkers Lake Rd., Wayzata, MN 55391

(2) Pulse Engineering, (619) 674-8100, P.O. Box 12236, San Diego, CA 92112

(3) Renco Electronics Inc., (516) 586-5566, 60 Jeffryn Blvd. East, Deer Park, NY 11729



## **PACKAGING INFORMATION**











**(1)** The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check<http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

**(3)** MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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# **PACKAGE MATERIALS INFORMATION**

## **TAPE AND REEL INFORMATION**

## **REEL DIMENSIONS**

*ii* Texas<br>
INSTRUMENTS





#### **TAPE DIMENSIONS**





## TAPE AND REEL INFORMATION

#### \*All dimensions are nominal



TEXAS<br>INSTRUMENTS

# **PACKAGE MATERIALS INFORMATION**

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## **MECHANICAL DATA**



## PLASTIC FLANGE-MOUNT PACKAGE



NOTES: A. All linear dimensions are in millimeters.

- **B.** This drawing is subject to change without notice.
- Body dimensions do not include mold flash or protrusion. Mold flash or protrusion not to exceed 0.005 (0,13) per side.  $\mathbb{C}.$
- $\hat{\mathbb{D}}$  Falls within JEDEC TO-263 variation BA, except minimum lead thickness, maximum seating height, and minimum body length.





NOTES: A. All linear dimensions are in millimeters.

- This drawing is subject to change without notice. **B.**
- C. Publication IPC-SM-782 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.
- F. This package is designed to be soldered to a thermal pad on the board. Refer to the Product Datasheet for specific thermal information, via requirements, and recommended thermal pad size. For thermal pad sizes larger than shown a solder mask defined pad is recommended in order to maintain the solderable pad geometry while increasing copper area.



KV (R-PZFM-T5)

PLASTIC FLANGE-MOUNT PACKAGE



- NOTES: A. All linear dimensions are in inches (millimeters).
	- **B.** This drawing is subject to change without notice.
	- All lead dimensions apply before solder dip. C.
	- The center lead is in electrical contact with the mounting tab. D.
	- $\sqrt{E}$  The chamfer is optional.
	- $\overbrace{f}$  Thermal pad contour optional within these dimensions.



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